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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	48MHz
Connectivity	I <sup>2</sup> C, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 10x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/pic18f2553-i-so">https://www.e-xfl.com/product-detail/microchip-technology/pic18f2553-i-so</a>



# MICROCHIP

# PIC18F2458/2553/4458/4553

## 28/40/44-Pin High-Performance, Enhanced Flash, USB Microcontrollers with 12-Bit A/D and nanoWatt Technology

### Universal Serial Bus Features:

- USB V2.0 Compliant
- Low Speed (1.5 Mb/s) and Full Speed (12 Mb/s)
- Supports Control, Interrupt, Isochronous and Bulk Transfers
- Supports up to 32 Endpoints (16 bidirectional)
- 1-Kbyte Dual Access RAM for USB
- On-Chip USB Transceiver with On-Chip Voltage Regulator
- Interface for Off-Chip USB Transceiver
- Streaming Parallel Port (SPP) for USB Streaming Transfers (40/44-pin devices only)

### Power-Managed Modes:

- Run: CPU On, Peripherals On
- Idle: CPU Off, Peripherals On
- Sleep: CPU Off, Peripherals Off
- Idle mode Currents Down to 5.8  $\mu$ A Typical
- Sleep mode Currents Down to 0.1  $\mu$ A Typical
- Timer1 Oscillator: 1.1  $\mu$ A Typical, 32 kHz, 2V
- Watchdog Timer: 2.1  $\mu$ A Typical
- Two-Speed Oscillator Start-up

### Special Microcontroller Features:

- C Compiler Optimized Architecture with Optional Extended Instruction Set
- 100,000 Erase/Write Cycle Enhanced Flash Program Memory Typical
- 1,000,000 Erase/Write Cycle Data EEPROM Memory Typical
- Flash/Data EEPROM Retention: > 40 Years
- Self-Programmable under Software Control
- Priority Levels for Interrupts
- 8 x 8 Single-Cycle Hardware Multiplier
- Extended Watchdog Timer (WDT):
  - Programmable period from 41 ms to 131s
- Programmable Code Protection
- Single-Supply 5V In-Circuit Serial Programming™ (ICSP™) via Two Pins
- In-Circuit Debug (ICD) via Two Pins
- Optional Dedicated ICD/ICSP Port (44-pin TQFP package only)
- Wide Operating Voltage Range (2.0V to 5.5V)

### Flexible Oscillator Structure:

- Four Crystal modes, Including High-Precision PLL for USB
- Two External Clock modes, up to 48 MHz
- Internal Oscillator Block:
  - 8 user-selectable frequencies, from 31 kHz to 8 MHz
  - User-tunable to compensate for frequency drift
- Secondary Oscillator using Timer1 @ 32 kHz
- Dual Oscillator Options allow Microcontroller and USB module to Run at Different Clock Speeds
- Fail-Safe Clock Monitor:
  - Allows for safe shutdown if any clock stops

### Peripheral Highlights:

- High-Current Sink/Source: 25 mA/25 mA
- Three External Interrupts
- Four Timer modules (Timer0 to Timer3)
- Up to 2 Capture/Compare/PWM (CCP) modules:
  - Capture is 16-bit, max. resolution 5.2 ns ( $T_{CY}/16$ )
  - Compare is 16-bit, max. resolution 83.3 ns ( $T_{CY}$ )
  - PWM output: PWM resolution is 1 to 10-bits
- Enhanced Capture/Compare/PWM (ECCP) module:
  - Multiple output modes
  - Selectable polarity
  - Programmable dead time
  - Auto-shutdown and auto-restart
- Enhanced USART module:
  - LIN bus support
- Master Synchronous Serial Port (MSSP) module supporting 3-wire SPI (all 4 modes) and I<sup>2</sup>C™ Master and Slave modes
- 12-Bit, up to 13-Channel Analog-to-Digital Converter module (A/D) with Programmable Acquisition Time
- Dual Analog Comparators with Input Multiplexing

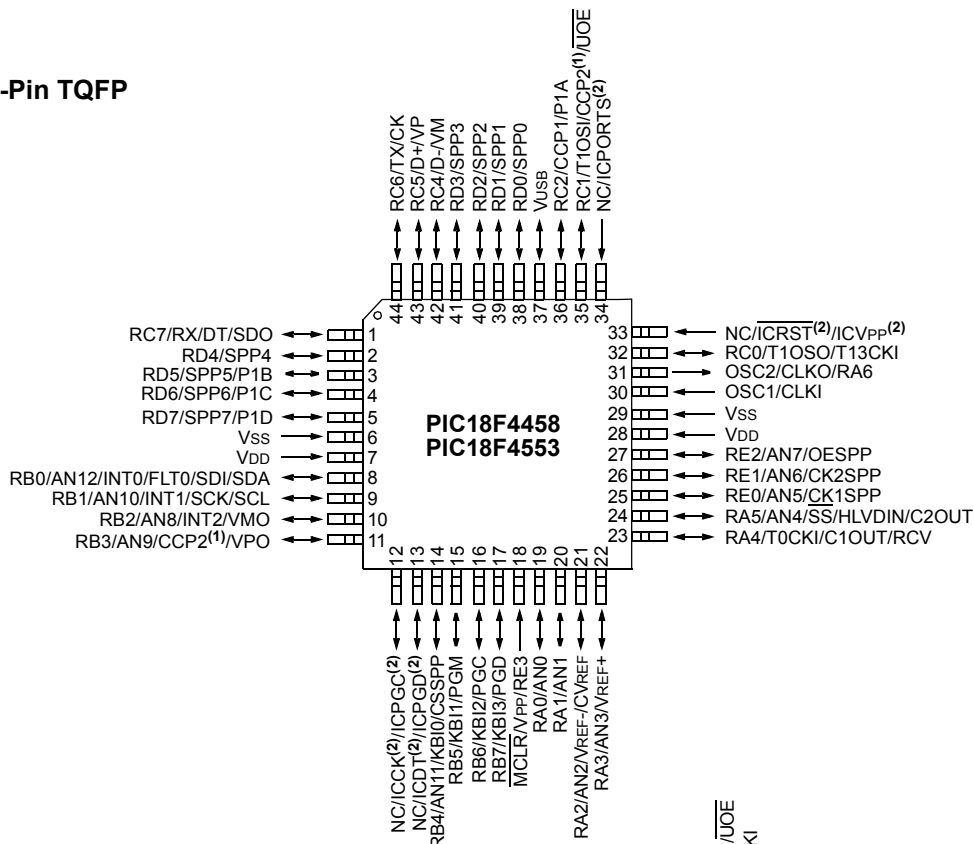
**Note:** This document is supplemented by the "PIC18F2455/2550/4455/4550 Data Sheet" (DS39632). See **Section 1.0 "Device Overview"**.

Device	Program Memory		Data Memory		I/O	12-Bit A/D (ch)	CCP/ECCP (PWM)	SPP	MSSP		EUSART	Comp.	Timers 8/16-Bit
	Flash (bytes)	# Single-Word Instructions	SRAM (bytes)	EEPROM (bytes)					SPI	Master I <sup>2</sup> C™			
PIC18F2458	24K	12288	2048	256	24	10	2/0	No	Y	Y	1	2	1/3
PIC18F2553	32K	16384			35	13	1/1	Yes					
PIC18F4458	24K	12288											
PIC18F4553	32K	16384											

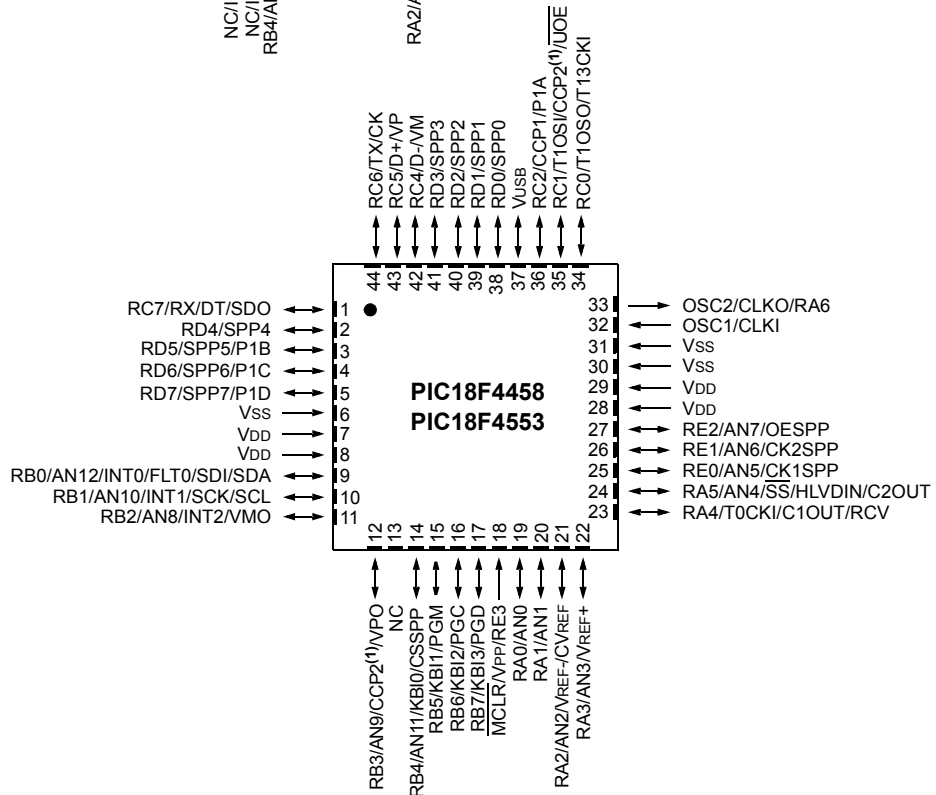
# PIC18F2458/2553/4458/4553

## Pin Diagrams (Continued)

### 44-Pin TQFP



### 44-Pin QFN



- Note** 1: RB3 is the alternate pin for CCP2 multiplexing.  
 2: Special ICPORT features are available only in 44-pin TQFP packages. See Section 25.9 "Special ICPORT Features" in the "PIC18F2455/2550/4455/4550 Data Sheet".

# PIC18F2458/2553/4458/4553

**TABLE 1-1: DEVICE FEATURES**

Features	PIC18F2458	PIC18F2553	PIC18F4458	PIC18F4553
Operating Frequency	DC – 48 MHz	DC – 48 MHz	DC – 48 MHz	DC – 48 MHz
Program Memory (Bytes)	24576	32768	24576	32768
Program Memory (Instructions)	12288	16384	12288	16384
Data Memory (Bytes)	2048	2048	2048	2048
Data EEPROM Memory (Bytes)	256	256	256	256
Interrupt Sources	19	19	20	20
I/O Ports	Ports A, B, C, (E)	Ports A, B, C, (E)	Ports A, B, C, D, E	Ports A, B, C, D, E
Timers	4	4	4	4
Capture/Compare/PWM Modules	2	2	1	1
Enhanced Capture/Compare/PWM Modules	0	0	1	1
Serial Communications	MSSP, Enhanced USART	MSSP, Enhanced USART	MSSP, Enhanced USART	MSSP, Enhanced USART
Universal Serial Bus (USB) Module	1	1	1	1
Streaming Parallel Port (SPP)	No	No	Yes	Yes
12-Bit Analog-to-Digital Converter Module	10 Input Channels	10 Input Channels	13 Input Channels	13 Input Channels
Comparators	2	2	2	2
Resets (and Delays)	POR, BOR, WDT, RESET Instruction, Stack Full, Stack Underflow, MCLR (optional), (PWRT, OST)	POR, BOR, WDT, RESET Instruction, Stack Full, Stack Underflow, MCLR (optional), (PWRT, OST)	POR, BOR, WDT, RESET Instruction, Stack Full, Stack Underflow, MCLR (optional), (PWRT, OST)	POR, BOR, WDT, RESET Instruction, Stack Full, Stack Underflow, MCLR (optional), (PWRT, OST)
Programmable High/Low-Voltage Detect	Yes	Yes	Yes	Yes
Programmable Brown-out Reset	Yes	Yes	Yes	Yes
Instruction Set	75 Instructions; 83 with Extended Instruction Set Enabled	75 Instructions; 83 with Extended Instruction Set Enabled	75 Instructions; 83 with Extended Instruction Set Enabled	75 Instructions; 83 with Extended Instruction Set Enabled
Packages	28-Pin SPDIP 28-Pin SOIC	28-Pin SPDIP 28-Pin SOIC	40-Pin PDIP 44-Pin QFN 44-Pin TQFP	40-Pin PDIP 44-Pin QFN 44-Pin TQFP
Corresponding Devices with 10-Bit A/D	PIC18F2455	PIC18F2550	PIC18F4455	PIC18F4550

# PIC18F2458/2553/4458/4553

TABLE 1-2: PIC18F2458/2553 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	SPDIP, SOIC			
RA0/AN0	2	I/O I	TTL Analog	PORTA is a bidirectional I/O port.  Digital I/O. Analog input 0.
RA0 AN0				
RA1/AN1	3	I/O I	TTL Analog	Digital I/O. Analog input 1.
RA1 AN1				
RA2/AN2/VREF-/CVREF	4	I/O I	TTL Analog	Digital I/O. Analog input 2.
RA2 AN2				
VREF-		I	Analog	A/D reference voltage (low) input.
CVREF		O	Analog	Analog comparator reference output.
RA3/AN3/VREF+	5	I/O I I	TTL Analog Analog	Digital I/O. Analog input 3. A/D reference voltage (high) input.
RA3 AN3				
VREF+				
RA4/T0CKI/C1OUT/RCV	6	I/O I	ST ST	Digital I/O. Timer0 external clock input.
RA4 T0CKI				
C1OUT		O	—	Comparator 1 output.
RCV		I	TTL	External USB transceiver RCV input.
RA5/AN4/SS/ HLVDIN/C2OUT	7	I/O I I I O	TTL Analog TTL Analog —	Digital I/O. Analog input 4. SPI slave select input. High/Low-Voltage Detect input. Comparator 2 output.
RA5				
AN4				
SS				
HLVDIN				
C2OUT	O	—	Comparator 2 output.	
RA6	—	—	—	See the OSC2/CLKO/RA6 pin.

**Legend:** TTL = TTL compatible input                      CMOS = CMOS compatible input or output  
ST = Schmitt Trigger input with CMOS levels        I = Input  
O = Output    P = Power

- Note 1:** Alternate assignment for CCP2 when CCP2MX Configuration bit is cleared.  
**Note 2:** Default assignment for CCP2 when CCP2MX Configuration bit is set.

# PIC18F2458/2553/4458/4553

**TABLE 1-2: PIC18F2458/2553 PINOUT I/O DESCRIPTIONS (CONTINUED)**

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	SPDIP, SOIC			
RB0/AN12/INT0/FLT0/SDI/SDA	21	I/O	TTL	PORTB is a bidirectional I/O port. PORTB can be software programmed for internal weak pull-ups on all inputs.
RB0				Digital I/O.
AN12				Analog input 12.
INT0				External interrupt 0.
FLT0				PWM Fault input (CCP1 module).
SDI				SPI data in.
SDA				I <sup>2</sup> C™ data I/O.
RB1/AN10/INT1/SCK/SCL	22	I/O	TTL	Digital I/O.
RB1				Analog input 10.
AN10				External interrupt 1.
INT1				Synchronous serial clock input/output for SPI mode.
SCK				Synchronous serial clock input/output for I <sup>2</sup> C mode.
SCL				
RB2/AN8/INT2/VMO	23	I/O	TTL	Digital I/O.
RB2				Analog input 8.
AN8				External interrupt 2.
INT2				External USB transceiver VMO output.
VMO		O	—	
RB3/AN9/CCP2/VPO	24	I/O	TTL	Digital I/O.
RB3				Analog input 9.
AN9				Capture 2 input/Compare 2 output/PWM 2 output.
CCP2(1)				External USB transceiver VPO output.
VPO		O	—	
RB4/AN11/KBI0	25	I/O	TTL	Digital I/O.
RB4				Analog input 11.
AN11				Interrupt-on-change pin.
KBI0		I	TTL	
RB5/KBI1/PGM	26	I/O	TTL	Digital I/O.
RB5				Interrupt-on-change pin.
KBI1				Low-Voltage ICSP™ Programming enable pin.
PGM		I/O	ST	
RB6/KBI2/PGC	27	I/O	TTL	Digital I/O.
RB6				Interrupt-on-change pin.
KBI2				In-Circuit Debugger and ICSP programming clock pin.
PGC		I/O	ST	
RB7/KBI3/PGD	28	I/O	TTL	Digital I/O.
RB7				Interrupt-on-change pin.
KBI3				In-Circuit Debugger and ICSP programming data pin.
PGD		I/O	ST	

**Legend:** TTL = TTL compatible input    CMOS = CMOS compatible input or output  
ST = Schmitt Trigger input with CMOS levels    I = Input  
O = Output    P = Power

**Note 1:** Alternate assignment for CCP2 when CCP2MX Configuration bit is cleared.  
**2:** Default assignment for CCP2 when CCP2MX Configuration bit is set.

# PIC18F2458/2553/4458/4553

**TABLE 1-3: PIC18F4458/4553 PINOUT I/O DESCRIPTIONS (CONTINUED)**

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	QFN	TQFP			
RB0/AN12/INT0/ FLT0/SDI/SDA	33	9	8			PORTB is a bidirectional I/O port. PORTB can be software programmed for internal weak pull-ups on all inputs.
RB0				I/O	TTL	Digital I/O.
AN12				I	Analog	Analog input 12.
INT0				I	ST	External interrupt 0.
FLT0				I	ST	Enhanced PWM Fault input (ECCP1 module).
SDI				I	ST	SPI data in.
SDA				I/O	ST	I <sup>2</sup> C™ data I/O.
RB1/AN10/INT1/SCK/ SCL	34	10	9			
RB1				I/O	TTL	Digital I/O.
AN10				I	Analog	Analog input 10.
INT1				I	ST	External interrupt 1.
SCK				I/O	ST	Synchronous serial clock input/output for SPI mode.
SCL				I/O	ST	Synchronous serial clock input/output for I <sup>2</sup> C mode.
RB2/AN8/INT2/VM0	35	11	10			
RB2				I/O	TTL	Digital I/O.
AN8				I	Analog	Analog input 8.
INT2				I	ST	External interrupt 2.
VM0				O	—	External USB transceiver VM0 output.
RB3/AN9/CCP2/VPO	36	12	11			
RB3				I/O	TTL	Digital I/O.
AN9				I	Analog	Analog input 9.
CCP2 <sup>(1)</sup>				I/O	ST	Capture 2 input/Compare 2 output/PWM 2 output.
VPO				O	—	External USB transceiver VPO output.
RB4/AN11/KBI0/CSSPP	37	14	14			
RB4				I/O	TTL	Digital I/O.
AN11				I	Analog	Analog input 11.
KBI0				I	TTL	Interrupt-on-change pin.
CSSPP				O	—	SPP chip select control output.
RB5/KBI1/PGM	38	15	15			
RB5				I/O	TTL	Digital I/O.
KBI1				I	TTL	Interrupt-on-change pin.
PGM				I/O	ST	Low-Voltage ICSP™ Programming enable pin.
RB6/KBI2/PGC	39	16	16			
RB6				I/O	TTL	Digital I/O.
KBI2				I	TTL	Interrupt-on-change pin.
PGC				I/O	ST	In-Circuit Debugger and ICSP programming clock pin.
RB7/KBI3/PGD	40	17	17			
RB7				I/O	TTL	Digital I/O.
KBI3				I	TTL	Interrupt-on-change pin.
PGD				I/O	ST	In-Circuit Debugger and ICSP programming data pin.

**Legend:** TTL = TTL compatible input      CMOS = CMOS compatible input or output  
 ST = Schmitt Trigger input with CMOS levels      I = Input  
 O = Output      P = Power

- Note 1:** Alternate assignment for CCP2 when CCP2MX Configuration bit is cleared.  
**2:** Default assignment for CCP2 when CCP2MX Configuration bit is set.  
**3:** These pins are No Connect unless the ICPRT Configuration bit is set. For NC/ICPORTS, the pin is No Connect unless ICPRT is set and the DEBUG Configuration bit is cleared.

# PIC18F2458/2553/4458/4553

TABLE 1-3: PIC18F4458/4553 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	QFN	TQFP			
RC0/T1OSO/T13CKI RC0 T1OSO T13CKI	15	34	32	I/O O I	ST — ST	PORTC is a bidirectional I/O port.  Digital I/O. Timer1 oscillator output. Timer1/Timer3 external clock input.
RC1/T1OSI/CCP2/ UOE RC1 T1OSI CCP2 <sup>(2)</sup> UOE	16	35	35	I/O I I/O O	ST CMOS ST —	Digital I/O. Timer1 oscillator input. Capture 2 input/Compare 2 output/PWM2 output. External USB transceiver OE output.
RC2/CCP1/P1A RC2 CCP1 P1A	17	36	36	I/O I/O O	ST ST TTL	Digital I/O. Capture 1 input/Compare 1 output/PWM1 output. Enhanced CCP1 PWM output, channel A.
RC4/D-/VM RC4 D- VM	23	42	42	I I/O I	TTL — TTL	Digital input. USB differential minus line (input/output). External USB transceiver VM input.
RC5/D+/VP RC5 D+ VP	24	43	43	I I/O I	TTL — TTL	Digital input. USB differential plus line (input/output). External USB transceiver VP input.
RC6/TX/CK RC6 TX CK	25	44	44	I/O O I/O	ST — ST	Digital I/O. EUSART asynchronous transmit. EUSART synchronous clock (see RX/DT).
RC7/RX/DT/SDO RC7 RX DT SDO	26	1	1	I/O I I/O O	ST ST ST —	Digital I/O. EUSART asynchronous receive. EUSART synchronous data (see TX/CK). SPI data out.

**Legend:** TTL = TTL compatible input  
ST = Schmitt Trigger input with CMOS levels  
O = Output  
CMOS = CMOS compatible input or output  
I = Input  
P = Power

- Note 1:** Alternate assignment for CCP2 when CCP2MX Configuration bit is cleared.  
**Note 2:** Default assignment for CCP2 when CCP2MX Configuration bit is set.  
**Note 3:** These pins are No Connect unless the ICPRT Configuration bit is set. For NC/ICPORTS, the pin is No Connect unless ICPRT is set and the DEBUG Configuration bit is cleared.



# PIC18F2458/2553/4458/4553

The analog reference voltage is software selectable to either the device's positive and negative supply voltage (VDD and VSS), or the voltage level on the RA3/AN3/VREF+ and RA2/AN2/VREF-/CVREF pins.

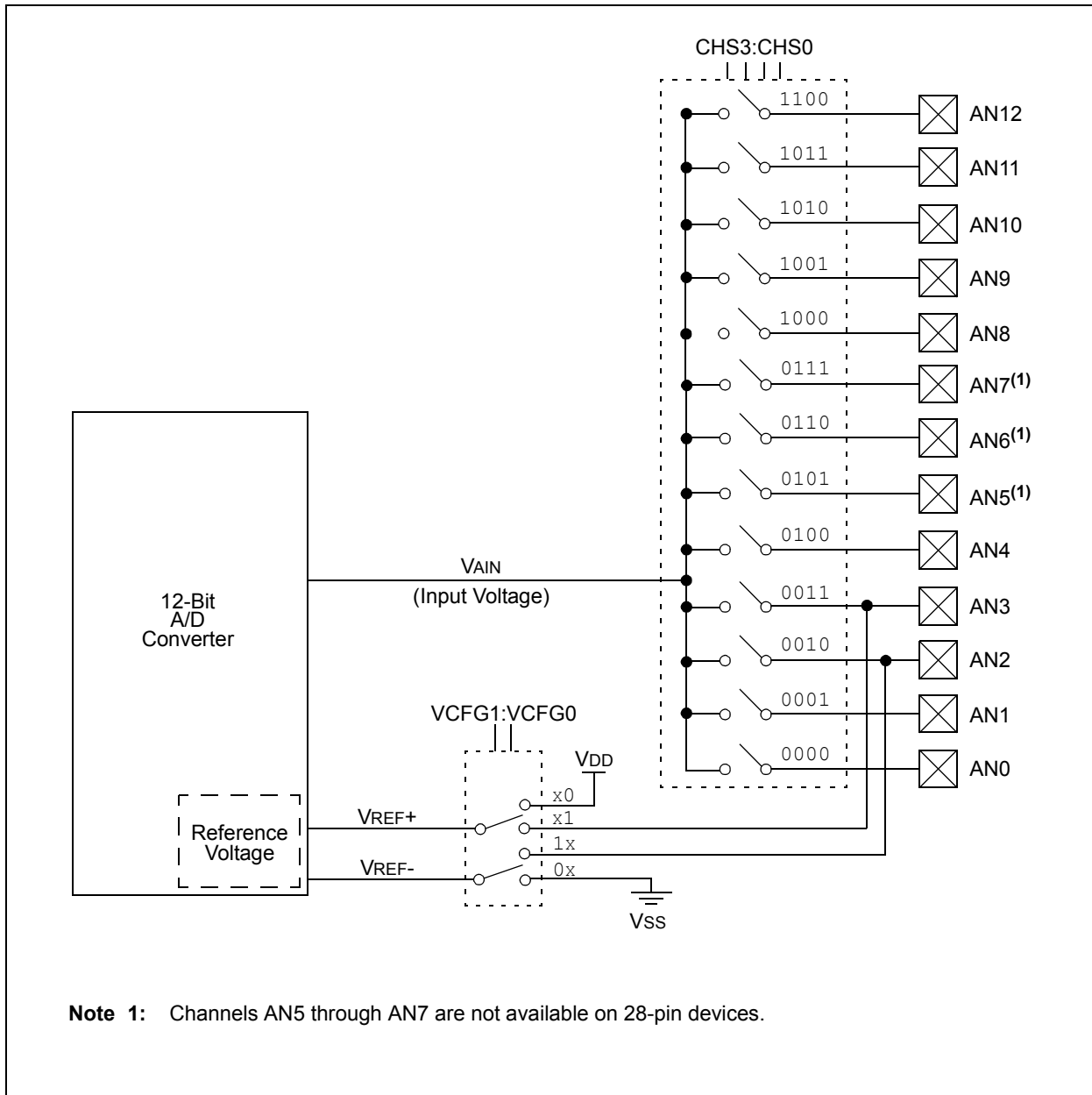
The A/D Converter has a unique feature of being able to operate while the device is in Sleep mode. To operate in Sleep, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

The output of the sample and hold is the input into the Converter, which generates the result via successive approximation.

A device Reset forces all registers to their Reset state. This forces the A/D module to be turned off and any conversion in progress is aborted.

Each port pin associated with the A/D Converter can be configured as an analog input or as a digital I/O. The ADRESH and ADRESL registers contain the result of the A/D conversion. When the A/D conversion is complete, the result is loaded into the ADRESH:ADRESL register pair, the GO/DONE bit (ADCON0 register) is cleared and the A/D Interrupt Flag bit, ADIF, is set. The block diagram of the A/D module is shown in Figure 2-1.

**FIGURE 2-1: A/D BLOCK DIAGRAM**



# PIC18F2458/2553/4458/4553

The value in the ADRESH:ADRESL registers is unknown following Power-on and Brown-out Resets, and is not affected by any other Reset.

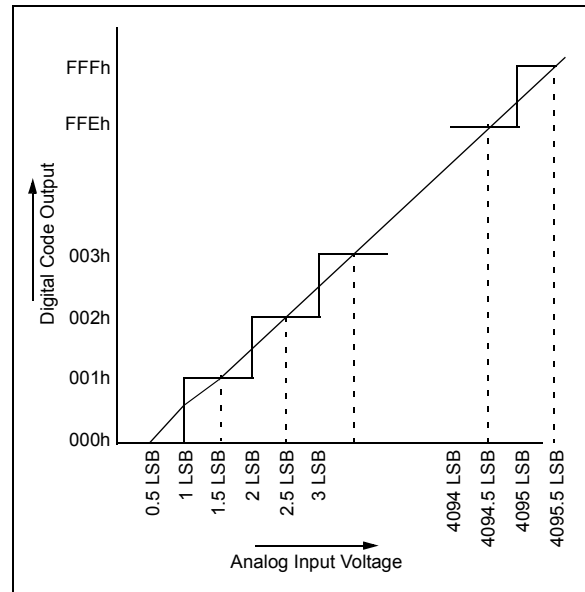
After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as an input. To determine acquisition time, see **Section 2.1 “A/D Acquisition Requirements”**. After this acquisition time has elapsed, the A/D conversion can be started. An acquisition time can be programmed to occur between setting the GO/DONE bit and the actual start of the conversion.

The following steps should be followed to perform an A/D conversion:

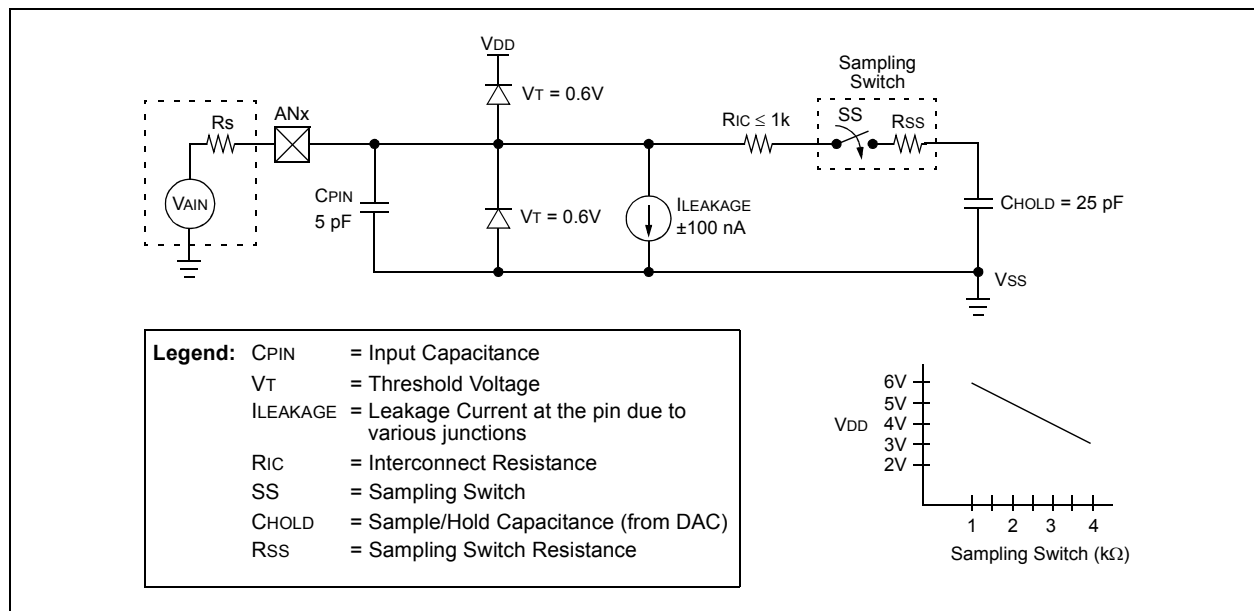
1. Configure the A/D module:
  - Configure analog pins, voltage reference and digital I/O (ADCON1)
  - Select A/D input channel (ADCON0)
  - Select A/D acquisition time (ADCON2)
  - Select A/D conversion clock (ADCON2)
  - Turn on A/D module (ADCON0)
2. Configure A/D interrupt (if desired):
  - Clear ADIF bit
  - Set ADIE bit
  - Set GIE bit
3. Wait the required acquisition time (if required).
4. Start conversion:
  - Set GO/DONE bit (ADCON0 register)

5. Wait for A/D conversion to complete, by either:
  - Polling for the GO/DONE bit to be cleared
 OR
  - Waiting for the A/D interrupt
6. Read A/D Result registers (ADRESH:ADRESL); clear bit ADIF, if required.
7. For next conversion, go to step 1 or step 2, as required. The A/D conversion time per bit is defined as T<sub>AD</sub>. A minimum wait of 2 T<sub>AD</sub> is required before the next acquisition starts.

**FIGURE 2-2: A/D TRANSFER FUNCTION**



**FIGURE 2-3: ANALOG INPUT MODEL**



# PIC18F2458/2553/4458/4553

## 2.1 A/D Acquisition Requirements

For the A/D Converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 2-3. The source impedance (Rs) and the internal sampling switch (Rss) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (Rss) impedance varies over the device voltage (VDD). The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 2.5 kΩ.** After the analog input channel is selected (changed), the channel must be sampled for at least the minimum acquisition time before starting a conversion.

**Note:** When the conversion is started, the holding capacitor is disconnected from the input pin.

To calculate the minimum acquisition time, Equation 2-1 may be used. This equation assumes that 1/2 LSB error is used (4096 steps for the 12-bit A/D). The 1/2 LSB error is the maximum error allowed for the A/D to meet its specified resolution.

Example 2-3 shows the calculation of the minimum required acquisition time, TACQ. This calculation is based on the following application system assumptions:

CHOLD	=	25 pF
Rs	=	2.5 kΩ
Conversion Error	≤	1/2 LSB
VDD	=	3V → Rss = 4 kΩ
Temperature	=	85°C (system max.)

### EQUATION 2-1: ACQUISITION TIME

$$\begin{aligned} TACQ &= \text{Amplifier Settling Time} + \text{Holding Capacitor Charging Time} + \text{Temperature Coefficient} \\ &= TAMP + TC + TCOFF \end{aligned}$$

### EQUATION 2-2: A/D MINIMUM CHARGING TIME

$$\begin{aligned} V_{HOLD} &= (V_{REF} - (V_{REF}/4096)) \cdot (1 - e^{-(Tc/CHOLD)(RIC + Rss + Rs)}) \\ \text{or} \\ Tc &= -(CHOLD)(RIC + Rss + Rs) \ln(1/4096) \end{aligned}$$

### EQUATION 2-3: CALCULATING THE MINIMUM REQUIRED ACQUISITION TIME

$$\begin{aligned} TACQ &= TAMP + TC + TCOFF \\ TAMP &= 0.2 \mu\text{s} \\ TCOFF &= (\text{Temp} - 25^\circ\text{C})(0.02 \mu\text{s}/^\circ\text{C}) \\ &\quad (85^\circ\text{C} - 25^\circ\text{C})(0.02 \mu\text{s}/^\circ\text{C}) \\ &\quad 1.2 \mu\text{s} \end{aligned}$$

Temperature coefficient is only required for temperatures > 25°C. Below 25°C, TCOFF = 0 μs.

$$\begin{aligned} TC &= -(CHOLD)(RIC + Rss + Rs) \ln(1/4096) \mu\text{s} \\ &\quad -(25 \text{ pF})(1 \text{ k}\Omega + 4 \text{ k}\Omega + 2.5 \text{ k}\Omega) \ln(0.0002441) \mu\text{s} \\ &\quad 1.56 \mu\text{s} \\ TACQ &= 0.2 \mu\text{s} + 1.56 \mu\text{s} + 1.2 \mu\text{s} \\ &\quad 2.96 \mu\text{s} \end{aligned}$$

# PIC18F2458/2553/4458/4553

## 3.0 SPECIAL FEATURES OF THE CPU

**Note:** For additional details on the Configuration bits, refer to the “PIC18F2455/2550/4455/4550 Data Sheet”, Section 25.1 “Configuration Bits”. Device ID information presented in this section is for PIC18F2458/2553/4458/4553 only.

PIC18F2458/2553/4458/4553 devices include several features intended to maximize reliability and minimize cost through elimination of external components. These include:

- Device ID Registers

## 3.1 Device ID Registers

The Device ID registers are “read-only” registers. They identify the device type and revision to device programmers, and can be read by firmware using table reads.

**TABLE 3-1: DEVICE IDs**

File Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Default/ Unprogrammed Value	
3FFFFEh	DEVID1	DEV2	DEV1	DEV0	REV4	REV3	REV2	REV1	REV0	xxxx xxxx <sup>(1)</sup>
3FFFFFh	DEVID2	DEV10	DEV9	DEV8	DEV7	DEV6	DEV5	DEV4	DEV3	xxxx xxxx <sup>(1)</sup>

**Legend:** x = unknown, u = unchanged

**Note 1:** See Register 3-1 and Register 3-2 for DEVID values. DEVID registers are read-only and cannot be programmed by the user.

## 4.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings (†)

Ambient temperature under bias .....	-40°C to +125°C
Storage temperature .....	-65°C to +150°C
Voltage on any pin with respect to VSS (except VDD and $\overline{\text{MCLR}}$ ) .....	-0.3V to (VDD + 0.3V)
Voltage on VDD with respect to VSS .....	-0.3V to +7.5V
Voltage on $\overline{\text{MCLR}}$ with respect to VSS ( <b>Note 2</b> ) .....	0V to +13.25V
Total power dissipation ( <b>Note 1</b> ) .....	1.0W
Maximum current out of VSS pin .....	300 mA
Maximum current into VDD pin .....	250 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0 or V <sub>I</sub> > VDD).....	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > VDD) .....	±20 mA
Maximum output current sunk by any I/O pin.....	25 mA
Maximum output current sourced by any I/O pin .....	25 mA
Maximum current sunk by all ports .....	200 mA
Maximum current sourced by all ports .....	200 mA

**Note 1:** Power dissipation is calculated as follows:

$$P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$$

- 2:** Voltage spikes below VSS at the  $\overline{\text{MCLR}}/\text{VPP}/\text{RE3}$  pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a “low” level to the  $\overline{\text{MCLR}}/\text{VPP}/\text{RE3}$  pin, rather than pulling this pin directly to VSS.

† **NOTICE:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

# PIC18F2458/2553/4458/4553

FIGURE 4-1: PIC18F2458/2553/4458/4553 VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)

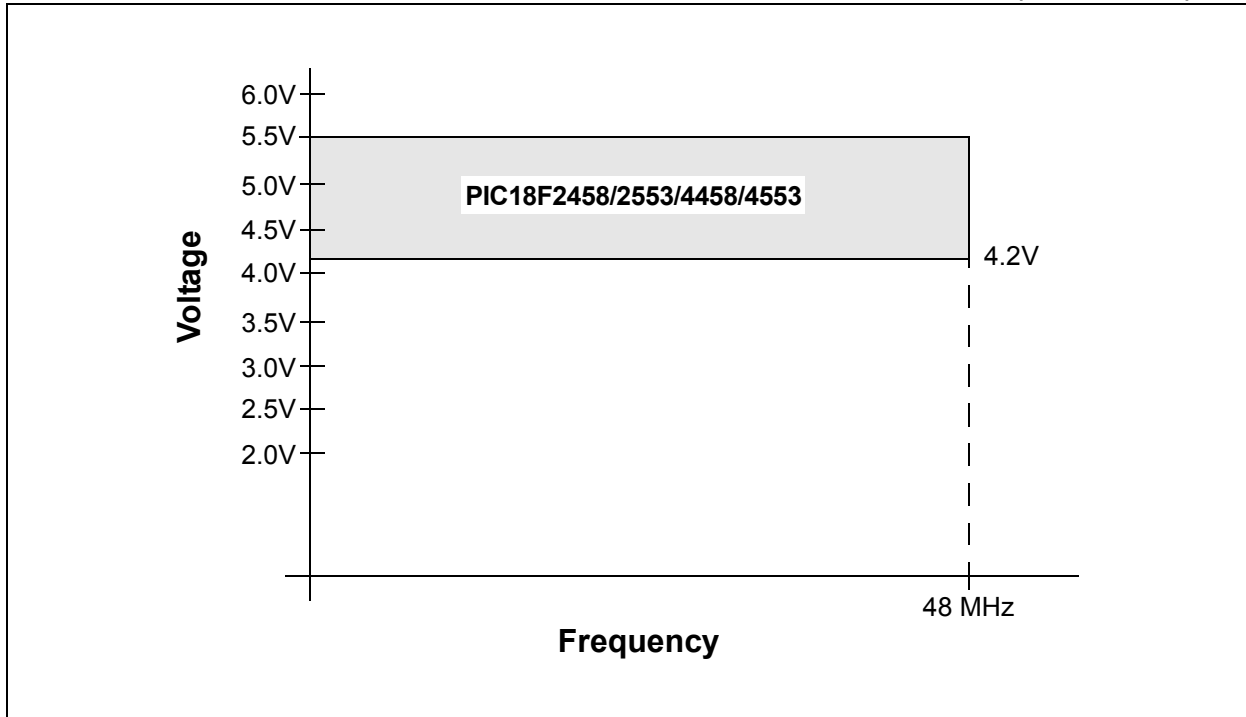
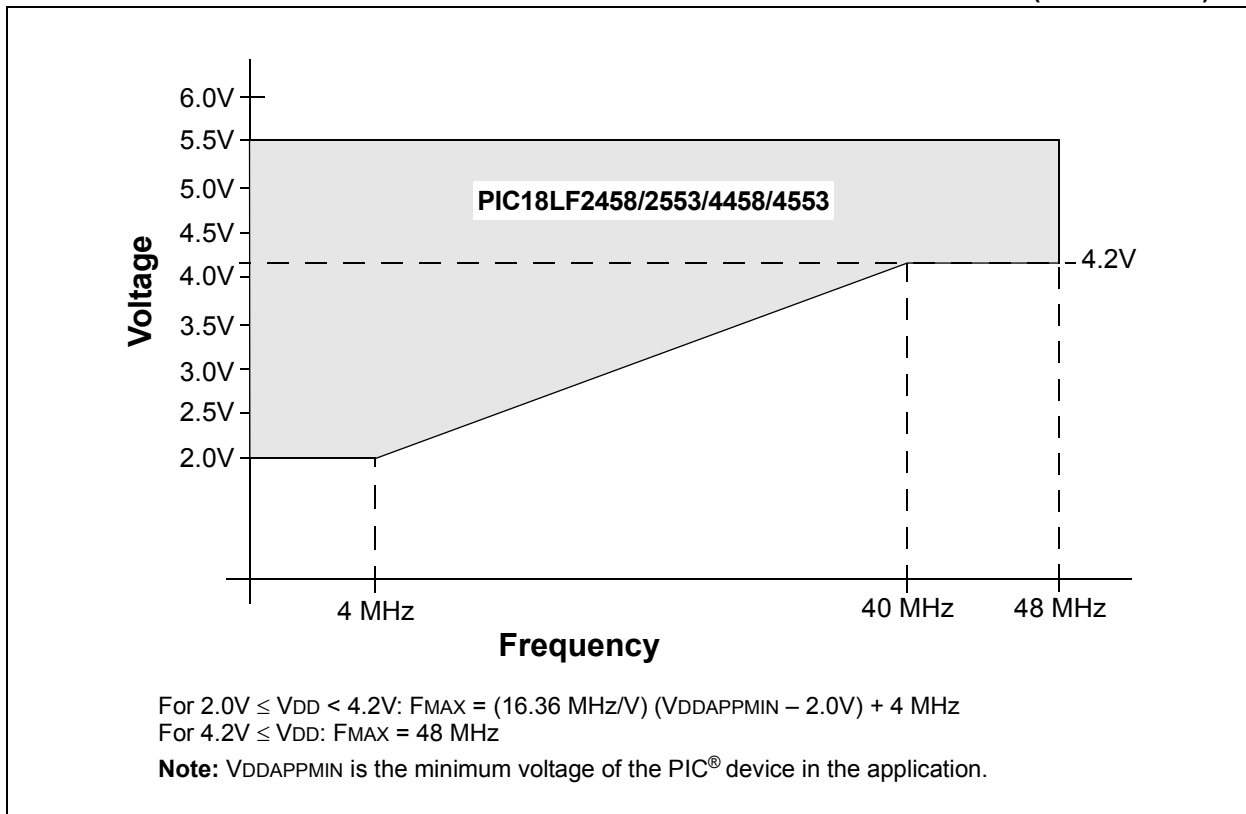


FIGURE 4-2: PIC18LF2458/2553/4458/4553 VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)



# PIC18F2458/2553/4458/4553

**TABLE 4-1: A/D CONVERTER CHARACTERISTICS: PIC18F2458/2553/4458/4553 (INDUSTRIAL)  
PIC18LF2458/2553/4458/4553 (INDUSTRIAL)**

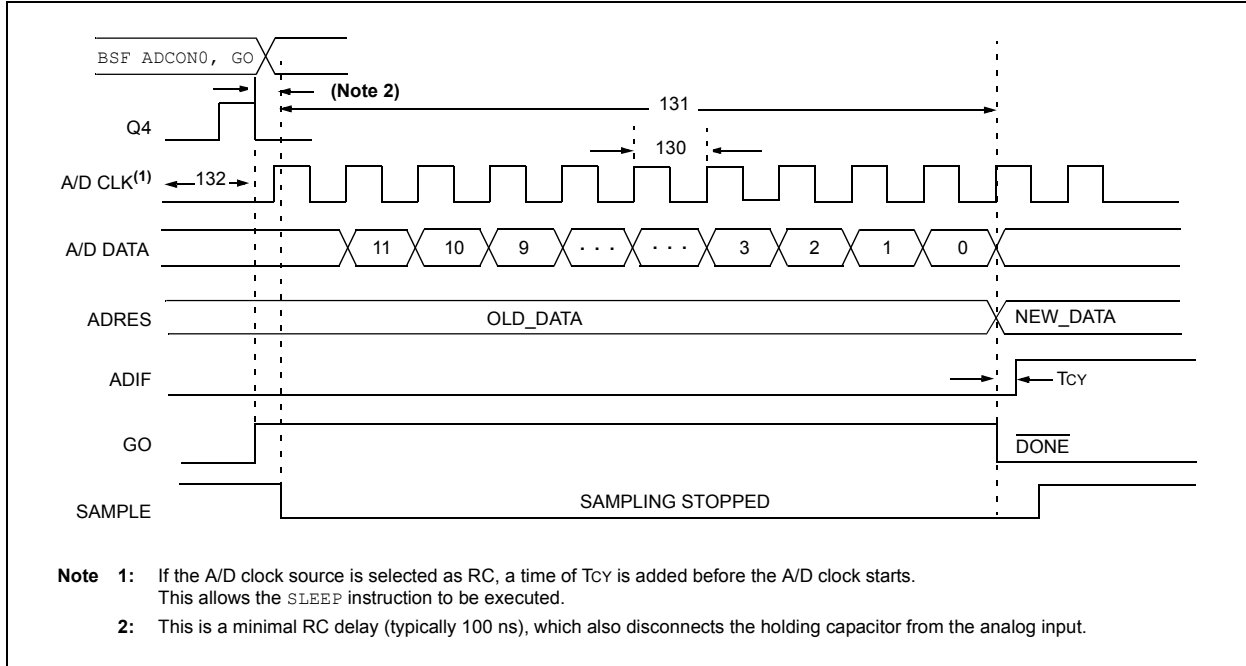
Param No.	Sym	Characteristic	Min	Typ	Max	Units	Conditions	
A01	NR	Resolution	—	—	12	bit		$\Delta V_{REF} \geq 3.0V$
A03	EIL	Integral Linearity Error	—	$\pm 1$	$\pm 2.0$	LSB	$V_{DD} = 3.0V$	$\Delta V_{REF} \geq 3.0V$
			—	—	$\pm 2.0$	LSB	$V_{DD} = 5.0V$	
A04	EDL	Differential Linearity Error	—	$\pm 1$	+1.5/-1.0	LSB	$V_{DD} = 3.0V$	$\Delta V_{REF} \geq 3.0V$
			—	—	+1.5/-1.0	LSB	$V_{DD} = 5.0V$	
A06	EOFF	Offset Error	—	$\pm 1$	$\pm 5$	LSB	$V_{DD} = 3.0V$	$\Delta V_{REF} \geq 3.0V$
			—	—	$\pm 3$	LSB	$V_{DD} = 5.0V$	
A07	EGN	Gain Error	—	$\pm 1$	$\pm 1.25$	LSB	$V_{DD} = 3.0V$	$\Delta V_{REF} \geq 3.0V$
			—	—	$\pm 2.00$	LSB	$V_{DD} = 5.0V$	
A10	—	Monotonicity	Guaranteed <sup>(1)</sup>			—	$V_{SS} \leq V_{AIN} \leq V_{REF}$	
A20	$\Delta V_{REF}$	Reference Voltage Range ( $V_{REFH} - V_{REFL}$ )	3	—	$V_{DD} - V_{SS}$	V	For 12-bit resolution	
A21	$V_{REFH}$	Reference Voltage High	$V_{SS} + 3.0V$	—	$V_{DD} + 0.3V$	V	For 12-bit resolution	
A22	$V_{REFL}$	Reference Voltage Low	$V_{SS} - 0.3V$	—	$V_{DD} - 3.0V$	V	For 12-bit resolution	
A25	$V_{AIN}$	Analog Input Voltage	$V_{REFL}$	—	$V_{REFH}$	V		
A30	$Z_{AIN}$	Recommended Impedance of Analog Voltage Source	—	—	2.5	k $\Omega$		
A50	IREF	$V_{REF}$ Input Current <sup>(2)</sup>	—	—	5	$\mu A$	During $V_{AIN}$ acquisition. During A/D conversion cycle.	
			—	—	150	$\mu A$		

**Note 1:** The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

- Note 2:**  $V_{REFH}$  current is from the RA3/AN3/ $V_{REF+}$  pin or  $V_{DD}$ , whichever is selected as the  $V_{REFH}$  source.  
 $V_{REFL}$  current is from the RA2/AN2/ $V_{REF-}/CV_{REF}$  pin or  $V_{SS}$ , whichever is selected as the  $V_{REFL}$  source.

# PIC18F2458/2553/4458/4553

**FIGURE 4-3: A/D CONVERSION TIMING**



**TABLE 4-2: A/D CONVERSION REQUIREMENTS**

Param No.	Symbol	Characteristic	Min	Max	Units	Conditions	
130	TAD	A/D Clock Period	PIC18FXXXX	0.8	12.5 <sup>(1)</sup>	μS	TOSC based, VREF ≥ 3.0V
			PIC18LFXXXX	1.4	25.0 <sup>(1)</sup>	μS	VDD = 3.0V; TOSC based, VREF full range
			PIC18FXXXX	—	1	μS	A/D RC mode
			PIC18LFXXXX	—	3	μS	VDD = 3.0V; A/D RC mode
131	T <sub>CV</sub>	Conversion Time (not including acquisition time) <sup>(2)</sup>	13	14	TAD		
132	T <sub>ACQ</sub>	Acquisition Time <sup>(3)</sup>	1.4	—	μS		
135	T <sub>SWC</sub>	Switching Time from Convert → Sample	—	(Note 4)			
137	T <sub>DIS</sub>	Discharge Time	0.2	—	μS		

- Note 1:** The time of the A/D clock period is dependent on the device frequency and the TAD clock divider.
- Note 2:** ADRES registers may be read on the following T<sub>CV</sub> cycle.
- Note 3:** The time for the holding capacitor to acquire the “New” input voltage when the voltage changes full scale after the conversion (VDD to VSS or VSS to VDD). The source impedance (R<sub>S</sub>) on the input channels is 50Ω.
- Note 4:** On the following cycle of the device clock.



## 5.0 PACKAGING INFORMATION

For packaging information, see the “*PIC18F2455/2550/4455/4550 Data Sheet*” (DS39632).

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# PIC18F2458/2553/4458/4553

## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>X</u>	<u>/XX</u>	<u>XXX</u>
Device	Temperature Range	Package	Pattern
Device	PIC18F2458/2553 <sup>(1)</sup> , PIC18F4458/4553 <sup>(1)</sup> , PIC18F2458/2553T <sup>(2)</sup> , PIC18F4458/4553T <sup>(2)</sup> ; V <sub>DD</sub> range 4.2V to 5.5V PIC18LF2458/2553 <sup>(1)</sup> , PIC18LF4458/4553 <sup>(1)</sup> , PIC18LF2458/2553T <sup>(2)</sup> , PIC18LF4458/4553T <sup>(2)</sup> ; V <sub>DD</sub> range 2.0V to 5.5V		
Temperature Range	I = -40°C to +85°C (Industrial) E = -40°C to +125°C (Extended)		
Package	PT = TQFP (Thin Quad Flatpack) SO = SOIC SP = Skinny PDIP P = PDIP ML = QFN		
Pattern	QTP, SQTP, Code or Special Requirements (blank otherwise)		

**Examples:**

- a) PIC18LF4553-I/P 301 = Industrial temp., PDIP package, Extended V<sub>DD</sub> limits, QTP pattern #301.
- b) PIC18LF2458-I/SO = Industrial temp., SOIC package, Extended V<sub>DD</sub> limits.
- c) PIC18F4458-I/P = Industrial temp., PDIP package, normal V<sub>DD</sub> limits.

**Note 1:** F = Standard Voltage Range  
 LF = Wide Voltage Range  
**2:** T = In tape and reel TQFP packages only.



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